



## G30 Models Differences

The table below describes the differences between the models.

Generic models - 8M Memory Chip						
#	MODEL	_____Description_____	UFL	eSIM	70 pin	Electrical Kit
1	F9000AAA	SM,8M,G30 GSM MDL N U.FL N ESIM N 70	NO	NO	NO	FCN6818A
2	F9100AAA	SM,8M,G30 GSM MDL W U.FL N ESIM N 70	YES	NO	NO	FCN6819A
3	F9200AAA	SM,8M,G30 GSM MDL W U.FL N ESIM W 70	YES	NO	YES	FCN6822A
4	F9300AAA	SM,8M,G30 GSM MDL N U.FL W ESIM N 70	NO	YES	NO	FCN6820A
5	F9400AAA	SM,8M,G30 GSM MDL W U.FL W ESIM N 70	YES	YES	NO	FCN6821A
6	F9500AAA	SM,8M,G30 GSM MDL W U.FL W ESIM W 70	YES	YES	YES	FCN6823A
Models with - 16M Memory Chip						
#	MODEL	_____Description_____	UFL	eSIM	70 pin	Electrical Kit
7	F9000ABA	SM,16M,G30 GSM MDL N U.FL N ESIM N 70	NO	NO	NO	FCN6824A
8	F9100ABA	SM,16M,G30 GSM MDL W U.FL N ESIM N 70	YES	NO	NO	FCN6825A
9	F9200ABA	SM,16M,G30 GSM MDL W U.FL N ESIM W 70	YES	NO	YES	FCN6828A
10	F9300ABA	SM,16M,G30 GSM MDL N U.FL W ESIM N 70	NO	YES	NO	FCN6826A
11	F9400ABA	SM,16M,G30 GSM MDL W U.FL W ESIM N 70	YES	YES	NO	FCN6827A
12	F9500ABA	SM,16M,G30 GSM MDL W U.FL W ESIM W 70	YES	YES	YES	FCN6829A

The same schematics and PCB layout design is used for all models – only difference in population of parts in the different models.

There are several connectivity options: one, as LGA (Land Grid Array) and two, through 70 pins connector – for LGA connectivity, the RF output may be through RF pad or through RF U-FL connector, while for 70 pins connector – only RF U-FL can be used.

The RF output in models F9100AxA, F9200AxA, F9400AxA, and F9500AxA is RF U-FL connector, while for F9000AxA and F9300AxA models RF output is through RF PAD (Bottom side).

For RF U-FL power out -

Inductor is placed in series with U.FL RF connector (L119), U.FL RF connector is populated, Inductor in series with LGA pad is DNP (Do Not Place).

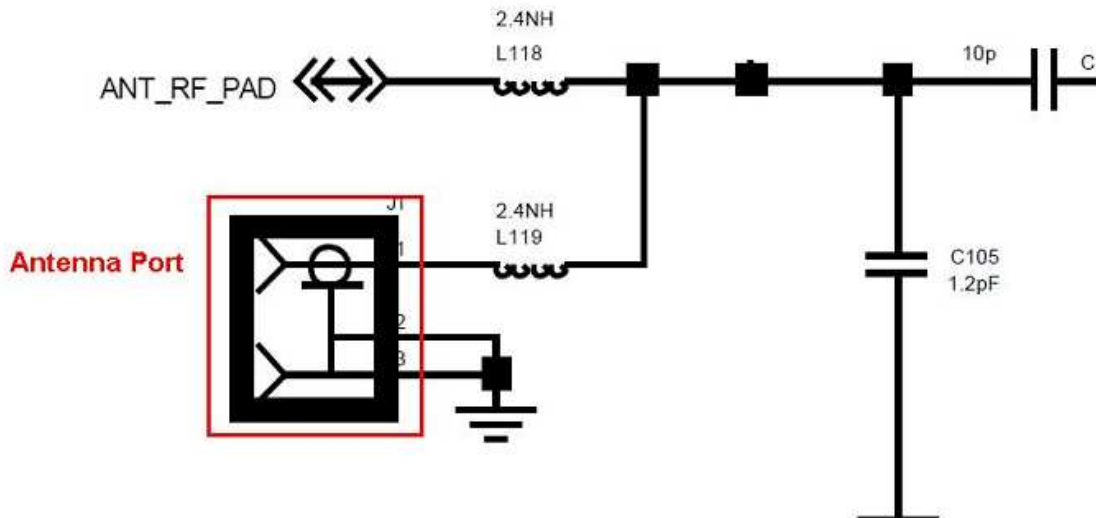
For LGA pad power out -

Inductor is placed in series LGA pad (L118), U-FL RF connector is not placed, Inductor in series with U.FL RF connector path is DNP

No change to circuit layout, all pads for the above mentioned parts exist in the layout.



**MOTOROLA**



More differences not related to RF output are described below:

Signal I/O

70 pin connector

Insulator is placed over the LGA pads

R220,R230,R221,R223 are placed

LGA pads

70 pin connector is J2 DNP

R220,R230,R221, R223 are DNP

Insulator for LGA pads is DNP

Note: All I/O lines are in parallel to both interfaces

No eSIM

External SIM

SIM I/O lines are passed through the LGA pads and 70 pins connector.

U107 (eSIM) is DNP

2 resistors in eSIM reset circuit as R222, R233 DNP

eSIM

2 resistors in eSIM reset circuit as placed R222, R233

U107 (eSIM) is placed

No change to circuit layout, all pads for the above mentioned parts exist in the layout.

Memory

8 M

IC102 placed

R213 placed

16 M

U102 placed.

R213 DNP

U101 placed